CLAIMS

WE CLAIM:

1. A method of bonding a ceramic material to a manufacturing tool comprising

   providing an adhesive composition comprising a resist adhesive resin and a solvent, wherein the solvent has a boiling point in the range of about 30°C to about 80°C;

   placing the adhesive composition onto a surface of the ceramic material;

   contacting the manufacturing tool with the adhesive composition on the surface of the ceramic material such that the tool and the ceramic material bond together; and

   subjecting the adhesive composition located between the tool and the ceramic material to conditions effective to substantially remove the solvent from the adhesive.

2. The method according to claim 1, wherein the resist adhesive resin is present in an amount of about 30 wt.% to about 80 wt.%.

3. The method according to claim 1, wherein the resist adhesive resin is present in an amount of about 40 wt.% to about 70 wt.%.

4. The method according to claim 1, wherein the resist adhesive resin is present in an amount of about 55 wt.% to about 65 wt.%.

5. The method according to claim 1, wherein the adhesive composition excludes solvents having boiling points above about 80°C.

6. The method according to claim 1, wherein the resist adhesive resin is selected from novolac resins, poly(ethylene-co-vinylalcohol), poly(2-hydroxyethylmethacrylate), cellulose polymers, or a combination thereof.

7. The method according to claim 6, wherein the resist adhesive resin is a novolac resin.

8. The method according to claim 1, wherein the solvent is selected from aliphatic and aromatic hydrocarbons, alcohols, ethers, ketones, esters, alcohol esters, ether alcohols, ether esters, ketone alcohols, ketone ethers, ketone esters, amides, nitriles, or a combination thereof.

9. The method according to claim 8, wherein the solvent is selected from acetone, isopropyl alcohol, dichloromethane, chloroform, tetrahydrofuran, ethyl acetate, methylethylketone or a combination thereof.

10. The method according to claim 9, wherein the solvent is acetone.

11. The method according to claim 1, wherein the conditions effective to remove the solvent from the adhesive comprise subjecting the adhesive to vacuum conditions.

12. The method according to claim 1, wherein the ceramic material is used to form sliders for hard disk drive applications.

13. The method according to claim 1, wherein the manufacturing tool is formed from a material selected from thermoplastic or thermoset polymer, metal, ceramic, glass, or a combination thereof.

14. The method according to claim 12, wherein the adhesive composition is placed on the air-bearing surface side of said ceramic material.

15. In a method of manufacturing a slider for a hard disk drive, wherein an adhesive is used to bond a ceramic material to a manufacturing tool, the improvement which comprises employing an adhesive composition comprising a resist adhesive resin and a solvent, wherein the solvent has a boiling point in the range of about 30°C to about 80°C.

16. The method according to claim 15, wherein the resin is a novolac resin.

17. The method according to claim 15, wherein the solvent is selected from acetone, isopropyl alcohol, dichloromethane, chloroform, tetrahydrofuran, ethyl acetate, methylethylketone or a combination thereof.

18. The method according to claim 15, wherein the solvent is acetone.

19. A method of improving the adhesive characteristics of an adhesive composition for use in bonding a ceramic material to a manufacturing tool comprising adding a solvent to a resist adhesive resin, wherein the solvent has a boiling point in the range of about 30°C to about 80°C.

20. The method according to claim 19, wherein the resist adhesive resin is present in an amount of about 30 wt.% to about 80 wt.%.

21. The method according to claim 19, wherein the adhesive composition excludes solvents having boiling points above about 80°C.

22. The method according to claim 19, wherein the resin is selected from novolac resins, poly(ethylene-co-vinylalcohol), poly(2-hydroxyethylmethacrylate), cellulose polymers, or a combination thereof.

23. The method according to claim 23, wherein the resin is a novolac resin.

24. The method according to claim 19, wherein the solvent is selected from aliphatic and aromatic hydrocarbons, alcohols, ethers, ketones, esters, alcohol esters, ether alcohols, ether esters, ketone alcohols, ketone ethers, ketone esters, amides, nitriles, or a combination thereof.

25. The method according to claim 24, wherein the solvent is selected from acetone, isopropyl alcohol, dichloromethane, chloroform, tetrahydrofuran, ethyl acetate, methylethylketone or a combination thereof.

26. The method according to claim 25, wherein the solvent is acetone.

27. An adhesive composition for use in the manufacture of sliders for hard disk drive applications, comprising a resist adhesive resin and a solvent, wherein the solvent has a boiling point in the range of about 30°C to about 80°C.

28. The adhesive composition according to claim 27, wherein the resin is selected from novolac resins, poly(ethylene-co-vinylalcohol), poly(2-hydroxyethylmethacrylate), cellulose polymers, or a combination thereof.

29. The adhesive composition according to claim 28, wherein the resin is a novolac resin.

30. The adhesive composition according to claim 27, wherein the solvent is selected from aliphatic and aromatic hydrocarbons, alcohols, ethers, ketones, esters, alcohol esters, ether alcohols, ether esters, ketone alcohols, ketone ethers, ketone esters, amides, nitriles, or a combination thereof.

31. The method according to claim 30, wherein the solvent is selected from acetone, isopropyl alcohol, dichloromethane, chloroform, tetrahydrofuran, ethyl acetate, methylethylketone or a combination thereof.

32. The adhesive composition according to claim 30, wherein the solvent is acetone.

33. The adhesive composition according to claim 27, wherein the solvent has a boiling point in the range of about 30°C to about 70°C.

34. The adhesive composition according to claim 27, wherein the adhesive composition excludes solvents having boiling points above about 80°C.